

DICING TAPE ATTACHING APPARATUS AND
DICING TAPE ATTACHING METHOD

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ABSTRACT OF THE DISCLOSURE

10 A dicing tape attaching apparatus (10) comprises a
fixed table (38) for supporting a mount frame (36), a
movable table (31) for supporting a wafer (20) with the
reverse surface thereof ground, and a height adjusting
unit (70) such as a screw jack for adjusting the height
of the movable table. When the dicing tape (3) is
15 attached on the mount frame and the wafer, the height
adjusting unit such as the screw jack so operates that
the height of the dicing tape attaching surface of the
wafer supported on the movable table coincides with the
height of the upper surface of the mount frame supported
20 on the fixed table. As a result, the wafer is prevented
from forming cuts, cracks and internal distortions.

Fig. 2